BRCS080N03DSC

Rev.A Aug.-2023

DATA SHEET

/ Descriptions

VRS0; ṂṂ Ŀ ᴥ Q ᵹ PRV ʆ ῶ Ẕ ⅂

Grxeoh Q0FKDQQHO PRVIHW lq d VRS0; Sodvwlf Sdfndjh1

/ Features

V_{DS}(V)=30V I_D=16A

$R_{DS(ON)}$@10V<8mΩ(Typ. 7.6mR)

$R_{DS(ON)}$)@4.5V<12mΩ(Typ. 10.8mR)

ῃ ғ ᵝ HF Product.

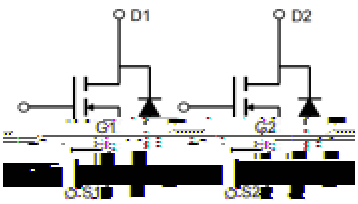
/ Applications

PE2QE2X PSF2YJD ق ـ ℓ ﻝ ЯΩ GF0GF ɔ ℸ U

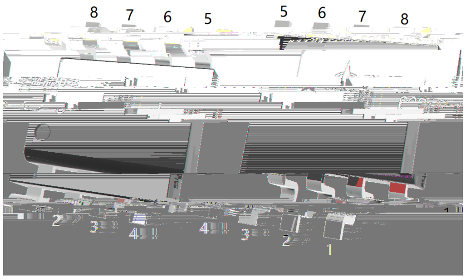
Kljk lxhtxhqf| Srlqw0ri0Ordg V|qfkurqrxv Exfn Frqyhuwhu iru PE2QE2X PSF2YJD/

Qhwz runlqj GF0GF Srzhu V|vwhp /Ordg Vzlwfk1

/ Equivalent Circuit



/ Pinning



PIN1 χ S1 PIN 2 χ G1 PIN 3 χ S2 PIN 4 χ G2

PIN 5 χ D2 PIN 6 χ D2 PIN 7 χ D1 PIN 8 χ D1

/ Marking

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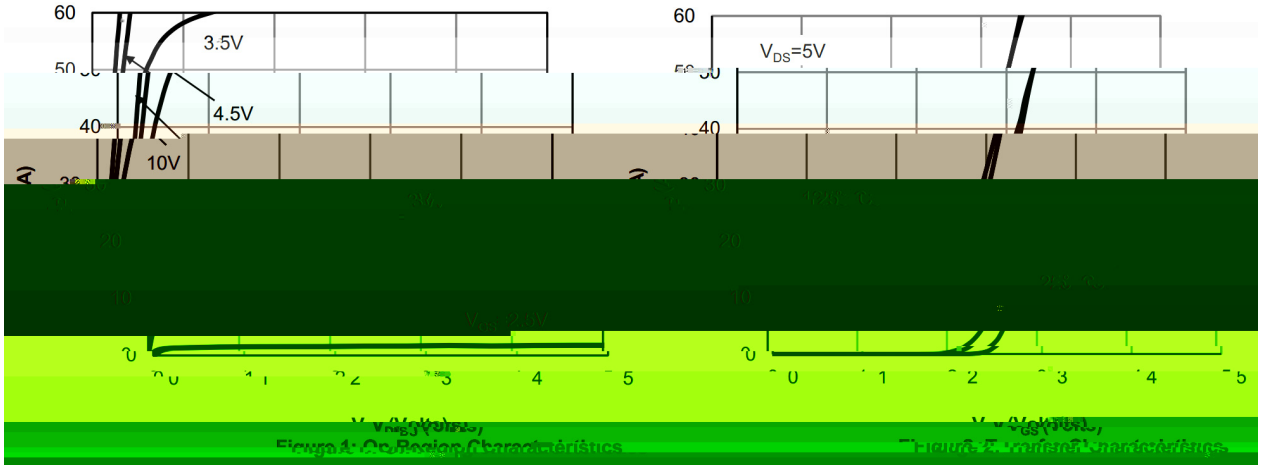
See Marking Instructions.

ν Ὢ Parameter	ɣ ᴺ Symbol	Ὢ Ө Rating	ᴅ ʮ Unit
Drain-Source Voltage	V_{DSS}	30	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current	I_D	16	A
Pulsed Drain Current	I_{DM}	59	A
Power Dissipation	P_D	3.2	W
Junction and Storage Temperature Range	T_J,T_{STG}	-55 to +150	
Maximum Junction-to-Ambient	$R_{\theta JA}$(Steady-State)	39	/W

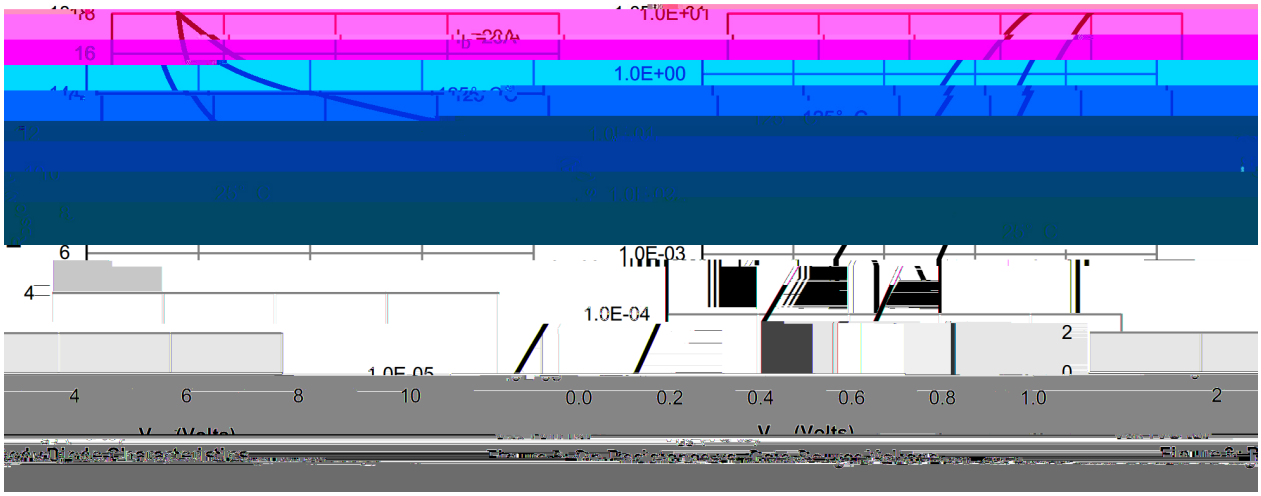
ν Ὢ Parameter	ɣ ᴺ Symbol	Test Conditions		ῳ ṇ Ө Min	Ɛ ȝ Ө Typ	ῳ Ө Max	ᴅ ʮ Unit
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V	I_D=250μA	30	35		V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=30V	V_{GS}=0V			1	μA
Gate-Body leakage current	I_{GSS}	V_{GS}=±20V	V_{DS}=0V			100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS}	I_D=250μA	1.0	1.7		

v ῍Ọ Parameter	Ɏ ᴺ Symbol	╜ ፧ᛨ Ʈ Test Conditions	ῳ ṇ Ӫ Min	Ɛ ȝ Ӫ Typ	ῳ ᶼ Ӫ Max	ᴅ ꞔ Unit
Turn-On Delay Time	$t_{d(on)}$	V_{DS}=15 V V_{GS}=10V R=10V =10V 880006 Tc(=15V)Tj385 1 Tf330008 0 T57TcTc( )Tj̵1<020c				

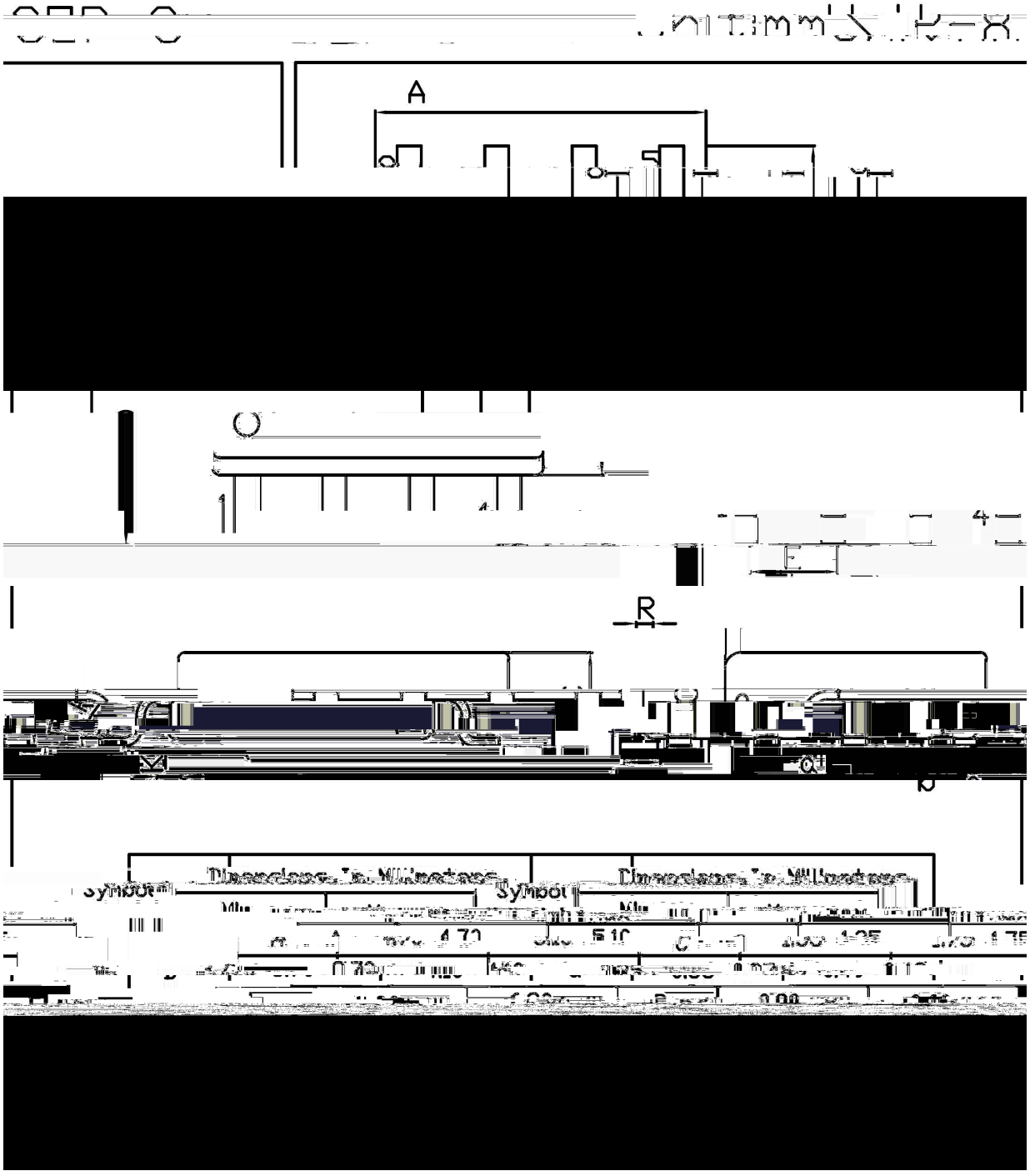
/ Electrical Characteristic Curve



Voltage

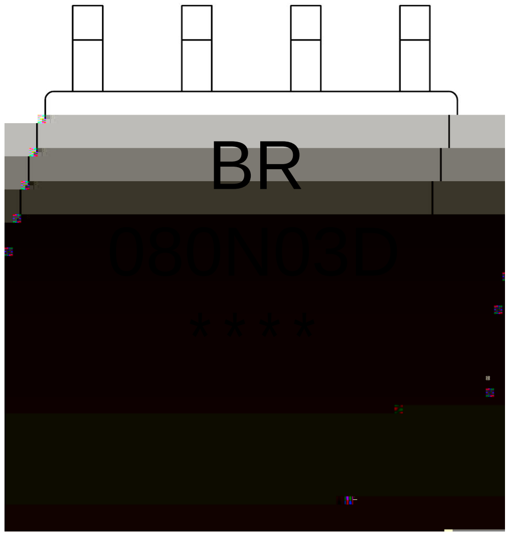


/ Package Dimensions



DATA SHEET

/ Marking Instructions



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Note:

BR:	Company Code
080N03D:	Product Type
****:	Lot No. Code, code change with Lot No

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

ب ˝ χ

1 Ĺ ♬ □ ỷ 150 Ḱ 180 ɬ ı ̀H ژ 60 Ḱ 90sec;

2 Š Ө □ ỷ 245 ° 5 ɬ ı ̀H ژ ̀Y ʌ ʁ 5 ° 0.5sec;

3 ì ˙ ٢ ˛ ɔ ѡ ỷ ʁ 2 Ḱ 10 ɬ /sec.

Note:

1.Preheating:150~180 ɬ , Time:60~90sec.

2.Peak Temp.:245 ° 5 ɬ , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ɬ /sec.

/ Resistance to Soldering Heat Test Conditions

605 ° 5 ɬ